EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	2604	(257/E23.011,E23.174,E25.013).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/08 14:59
L11	17	"3604989"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:35
L12	21	"3799802"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 15:49
L13	1	"3799802"	USOCR	OR	ON	2006/03/08 17:10
L14	0	"5767001"	USOCR	OR	ON	2006/03/08 17:11
L15	46	"5767001"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:06
L16	3	"703573".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:06
L17	130	Masuda and Kazuhiro	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L18	3	L17 and level and substrate and interlayer adj dielectric	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L19	8575	through-hole and (cu copper)	US-PGPUB; USPAT	OR	OFF	2006/03/08 18:54
L20	610	through-hole and (cu copper) and passivation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54

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L21	5297	(257/758,774,776).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/08 18:54
L22	379	L21 and through-hole	US-PGPUB; USPAT	OR	ON	2006/03/08 18:54
L23	7662	(contact-hole through-hole via) with interlayer	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L24	6626	(contact-hole through-hole via) with interlayer and substrate	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L25	26852	(contact-hole through-hole via) and interlayer	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L26	576	(contact-hole)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:54
L27	81583	(through-hole)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:54
L28	2587760	via	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:54
L29	2643551	L26 or L27 or L28	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:54
L30	8479	L29 with interlayer	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:54
L31	7326	L30 and substrate	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:54

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L32	116485	silicon adj substrate	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L33	2205	L30 and L32	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L34	58731	(contact-hole through-hole)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L35	13	through-hole and (cu copper) and passivation and hard adj mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L36	97	"4897708"	US-PGPUB; USPAT	OR	ON	2006/03/08 18:54
L37	12	(US-20030210534-$ or US-20040251554-$ or US-20040207089-$).did. or (US-6848177-$ or US-6486549-$ or US-5399898-$ or US-5432999-$ or US-6184060-$ or US-4954875-$ or US-4728627-$ or US-6664129-$ or US-5394013-$).did.	US-PGPUB; USPAT	OR	OFF	2006/03/08 18:54
L38	12	L37 and (contact-hole through-hole via)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L39	3	L37 and L23	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54

EAST Search History

L40	19	(US-20020017710-$ or US-20030008417-$ or US-20030183921-$ or US-20040164418-$).did. or (US-4652970-$ or US-4902637-$ or US-5055914-$ or US-5192988-$ or US-5229647-$ or US-5404046-$ or US-5637925-$ or US-5973927-$ or US-5682062-$ or US-6322903-$ or US-6486549-$ or US-6566232-$ or US-6664129-$ or US-6717254-$ or US-6753205-$).did.	US-PGPUB; USPAT	OR	OFF	2006/03/08 18:54
L41	4640	L31 and electrode	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:54
L42	249	L34 with L32	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54
L43	25	L30 and L42	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/03/08 18:54